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(57) **ABSTRACT**

An upper circuit board body has a first upper main surface and a first lower main surface. A lower circuit board body has a second upper main surface and a second lower main surface. A lower circuit board first mounting electrode and one or more lower circuit board second mounting electrodes are disposed on the second upper main surface. A first component is mounted on the one or more lower circuit board second mounting electrodes. A first conductor member is mounted on the lower circuit board first mounting electrode and is disposed on the left of the first component. A second conductor member is disposed on the first lower main surface, is connected to the upper end of the first conductor member, and overlaps at least a part of the first component as viewed in the downward direction.

